High Winding Ratio, High Frequency, Ultracompact Step-Up **Transformers with Laminated Metallic Magnetic Cores** Tao Zhang, Zoe Nelson, Mark G. Allen

Philadelphia, **Pennsylvania USA** Oct. 24-27, 2021

INTRODUCTION

- Miniaturization trends of electronic components require corresponding miniaturization of power supply modules
- Passive components such as transformers typically comprise the largest volume fractions of such modules
- Transformer size can be reduced by adopting advanced magnetic core materials
- Compared to ferrites, metallic alloys have high saturation flux density, enabling high energy density, but low electrical resistivity, causing eddy current loss at high frequency
- Laminated metallic alloy cores can suppress eddy currents while maintaining large magnetic volume

Prope Flux densi **Relative perm** Resistivity

Mass density

TRANSFORMER DESIGN & FABRICATION





	Magnetic Core Dimensions								
Sample	W	L	t _m	t_{m0}	W_{w}	W_1	N _p	N_s	
No.	(mm)	(mm)	(mm)	(µm)	(mm)	(mm)	(turns)	(turns)	
S1	0.8	1.2	0.27	1	0.39	0.3	8	80	
S2	1.2	1.2	0.24	2	0.73	0.3	12	120	
S3	1.2	1.2	0.24	3	0.73	0.3	12	130	
S 4	1.2	1.2	0.18	3	0.73	0.3	12	130	
S5	1.2	1.2	0.18	6	0.73	0.3	12	130	

 t_m : effective core thickness, t_{m0} : individual magnetic layer thickness, N_p : primary coil turn number, N_s: secondary coil turn number.

- Transformer core comprises a rectangular, multilayer laminated structure, with alternating permalloy (NiFe) and electrical insulation layers
- Two ring-like features at diagonal ends of the core assist in lamination self-assembly
- Individual magnetic lamination thicknesses (t_{m0}) are designed up to the NiFe skin depth at 2 MHz ($6.3 \mu m$)
- Except for S1, the targeted primary and secondary inductance for these transformers are above 2 μ H and 200 µH

- (b)
- (c)

KEY CONTRIBUTIONS

- High winding ratio, ultracompact step-up transformers for DC-DC converters
- Primary and secondary inductances in microhenry and hundreds of microhenry ranges, capable for high power handling
- Volume and weight less than commercial devices with similar inductances, showing promise for use in spaceconstrained electronic systems

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	Magnetic Materials					
ties	Ferrite	Metallic Alloys				
$\mathbf{x} \mathbf{y} \mathbf{B}_{\mathbf{s}}(\mathbf{T})$	< 0.5	1-2				
neability μ _r	< 100	> 150				
$\mathcal{O}_{\mathrm{m}}\left(\Omega\cdot\mathrm{m}\right)$	> 10 ⁻³	< 10-7				
	Winding Materials					
	Copper	Aluminum				
ρ (g/cm ³)	8.96	2.7				

Transformer weight can be further reduced by replacing copper winding with aluminum



Laminated magnetic core fabrication is facilitated using a hierarchical approach

Sequential electrodeposition is used to create NiFe/Cu multilayer constructs

Self-assembly is exploited to transform the multilayer constructs into core segments

Multiple core segments could be further assembled into thicker cores by repeating the previous procedure

TRANSFORMER CHARACTERIZATION

- Transformers exhibit high primary and secondary inductance values, which are maintained up to their resonance frequencies in the MHz range
- Inductance ratio between primary and secondary is smaller than the square of the turns ratio, attributable to magnetic coupling of less than unity in these devices
- Calculated effective permeability of the magnetic cores is close to 600, and does not change significantly with increasing individual magnetic layer thickness
- Except for S1, all transformers show coupling coefficients of 0.9-0.95 in frequency ranges of interest
- The measured step-up ratio of S2 is 7.8 at 0.4 MHz and increases to 10 at 1.6 MHz. With a primary voltage of 3.8 V peak to peak, a secondary voltage of 34.6 V peak to peak is observed
- Fabricated transformer is tested in a customized flyback converter circuit
- With a 5 V input voltage and a 100 $k\Omega$ load resistor, an output voltage of 112 V is observed, and calculated power delivered to the load resistor is 125 mW
- The fabricated transformers show 7 times higher inductance per volume and 5 times higher inductance per weight compared to commercial coupled inductors

This work was supported by the Defense Advanced Research Projects Agency, contract number HR0011-19-C-0039, under the supervision of Dr. R. Polcawich. Microfabrication took place in the Singh Center for Nanotechnology at the University of Pennsylvania, which is supported by the NSF National Nanotechnology Coordinated Infrastructure Program under grant NNCI-2025608. Technical discussions with Dr. Minsoo Kim of Apple are gratefully acknowledged.



relative laminated

Sample	L _p at 50	L _s at	L _p at	L _s at 1 MH ₇	R _p at	R_s at 50	R _p at	R _s at	f _{0p}
No.	μH)	kHz	MHz	(μH)	kHz	kHz	MHz	MHz	(NIHZ
		(µH)	(µH)		(Ω)	(Ω)	(Ω)	(Ω)	
S1	0.66	67	0.66	60	1.2	4.7	1.4	21	4.6
S2	2	175	2.02	180	9	10	12	137	3.1
S3	2.96	312	3.34	273	4.3	33	6.5	179	2.6
S4	1.95	198	1.97	200	3.6	32	4.9	144	2.9
S5	2.75	253	2.2	234	1.6	13	5.4	369	2.6

 L_p : primary inductance, L_s : secondary inductance, R_p : primary resistance, R_s : secondary resistance, f_{0p} : primary self-resonance frequency, f_{0s} : secondary self-resonance frequency.



ACKNOWLEDGEMENTS



